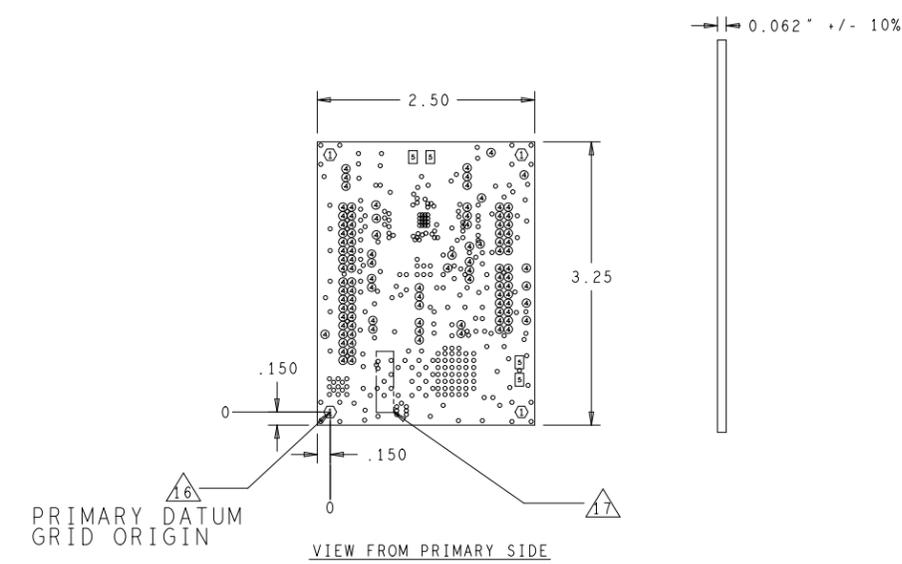


NOTES (UNLESS OTHERWISE SPECIFIED):

1. THIS DRAWING SPECIFIES THE REQUIREMENTS FOR A PRINTED WIRING BOARD IN ACCORDANCE WITH SPECIFICATION IPC-6012 CLASS 2 (LATEST REVISION).
2. THE PWB MUST BE LEAD FREE ASSEMBLY PROCESS COMPATIBLE AND MUST BE ABLE TO HANDLE A MINIMUM OF 5 CYCLES AT 260 DEGREES CELSIUS FOR 10 SECONDS.
3. BASE MATERIAL - LAMINATE AND PREPREG SHALL MEET IPC-4101D-26, 83 or 98  
Tg - MUST BE GREATER THAN OR EQUAL TO 150 DEGREES CELSIUS.  
Td - MUST BE GREATER THAN OR EQUAL TO 330 DEGREES CELSIUS.
4. COPPER FOIL WEIGHT - SEE STACKUP DETAIL 'A'
5. CHARACTERISTIC IMPEDANCE - NONE
6. MINIMUM CONDUCTIVE WIDTH/SPACING TO BE .010"/.007"
7. PLATING FINISH: A. BOTH SIDES ENIG; TO MEET THE REQUIREMENTS OF IPC-4552 (LATEST REVISION).
8. ALL THROUGH HOLE VIAS MAY BE PLATED SHUT.
9. SOLDERMASK - TO MEET THE REQUIREMENTS OF IPC-SM-840E (OR LATEST REVISION). GREEN COLOR, BOTH SIDES. MODIFICATION OF SOLDERMASK IS NOT ALLOWED WITHOUT WRITTEN PERMISSION FROM NXP. TYPE: LPI OR EQUIVALENT.  
A. LOCATION = +/- .002" OF PLATED PADS.  
B. DIAMETER OR SIZE = +/- .002 OF ORIGINAL DATA
10. SILKSCREEN - WHITE EPOXY OR ACRYLIC INK, BOTH SIDES. NO SILKSCREEN ON ANY EXPOSED COPPER FEATURE.
11. ELECTRICAL TEST - 100% IPCD356.
12. PRINTED WIRING BOARD IS TO BE INDIVIDUALLY BAGGED.
13. DFM CHECK MUST BE RUN ON THE GERBER BEFORE BUILDING BOARDS, UNLESS PRIOR APPROVAL IS GIVEN IN WRITING BY NXP.
14. TEARDROPS MAY BE ADDED AT THE FAB HOUSE TO ALL SIGNAL LAYERS.
15. TWO SOLDER SAMPLES TO BE PROVIDED.
16. BASIC GRID INCREMENT AT 1:1 IS 0.0001.
17. SUPPLIER MARKINGS - ON SECONDARY SIDE ONLY, WHERE SHOWN, MUST BE UL RECOGNIZED AND MUST HAVE AN ID THAT CONFORMS TO UL94V-0
18. THE PWB WILL BE MARKED AS LEAD FREE BY USE OF AN INK STAMP (Pb)
19. THE PWB WILL BE MARKED AS LEAD FREE PROCESS COMPATIBLE BY USE OF AN INK STAMP (260°C)
20. ALL PLATED AND NON-PLATED THROUGH HOLES ARE TO BE DRILLED AT PRIMARY DRILL STEP. ALL HOLE LOCATION TOLERANCES ARE TO BE +/- .002 IN REFERENCE TO THE PRIMARY DATUM UNLESS OTHERWISE SPECIFIED.
21. FINISHED PCB MUST BE PANELIZED FOR ASSEMBLY ACCORDING TO CONTRACT MANUFACTURERS REQUIREMENTS. THE ADDITION OF RAILS AND .125" NON-PLATED TOOLING HOLES ARE AT THE DISCRETION OF CONTRACT MANUFACTURER. PANELIZATION MUST BE APPROVED BY CONTRACT MANUFACTURER.
22. THE MANUFACTURE HAS THE OPTION TO ADD COPPER THIEVING ON OUTER AND INNER LAYERS, KEEP A MINIMUM DISTANCE OF .100" FROM ANY BOARD FEATURES.

REVISIONS				
ZONE	REV	DESCRIPTION	DATE	APPROVED
	A	ORIGINAL RELEASE	04-20-17	J.R.
	A1	SILKSCREEN CHANGE	07-24-17	J.R.



DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
⊙	10.0	+0.0/-10.0	PLATED	304
⊙	40.0	+3.0/-3.0	PLATED	105
⊙	51.0	+3.0/-3.0	PLATED	4
⊙	116.0	+3.15/-0.0	PLATED	4

FINISHED Cu WEIGHT

LAYER 1	COMPONENT SIDE	1.0 oz.
LAYER 2	GROUND PLANE	0.5 oz.
LAYER 3	GROUND PLANE	0.5 oz.
LAYER 4	GROUND PLANE	1.0 oz.

DETAIL A  
LAYER STACKUP  
SCALE: NONE

PART NO. 170-29799		NXP SEMICONDUCTORS	
<input type="checkbox"/> COMPANY PUBLIC <input checked="" type="checkbox"/> COMPANY INTERNAL <input type="checkbox"/> COMPANY CONFIDENTIAL		6501 WILLIAM CANNON DRIVE WEST AUSTIN, TEXAS 78735 USA TITLE: PRINTED WIRING BOARD FRDM-33926ESEVM	
UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES ARE: DECIMALS .XX .01 .XXX .005 ANGLES D-30° ✓ RMS ALL MACHINED SURFACES BREAK ALL SHARP EDGES AND CORNERS. REMOVE BURRS. UNDERLINED DIM. NOT TO SCALE. THIRD ANGLE ORTHOGRAPHIC PROJECTION IS USED.		APPROVALS DRAWN WAYNE ANDERSON CHECKED JORGE RODRIGUEZ DESIGN ENGINEER WAYNE ANDERSON	DATE 07-24-17 07-24-17 07-24-17
SCALE 1/1	DO NOT SCALE DRAWING	SHEET 1 OF 1	REV A1